SOT1780-7

WLCSP36, wafer level chip-scale package; 36 bumps; 0.4 mm pitch, 2.62 mm x 2.51 mm x 0.525 mm body

4 October 2017 | Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package type industry code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	18-9-2017
Manufacturer package code	SOT1780-7

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	2.62	-	mm
E	package width		-	-	2.51	-	mm
A	seated height		-	-	0.525	-	mm
e	nominal pitch		-	-	0.4	-	mm
n_2	actual quantity of termination		-	-	36	-	A/A

2. Package outline

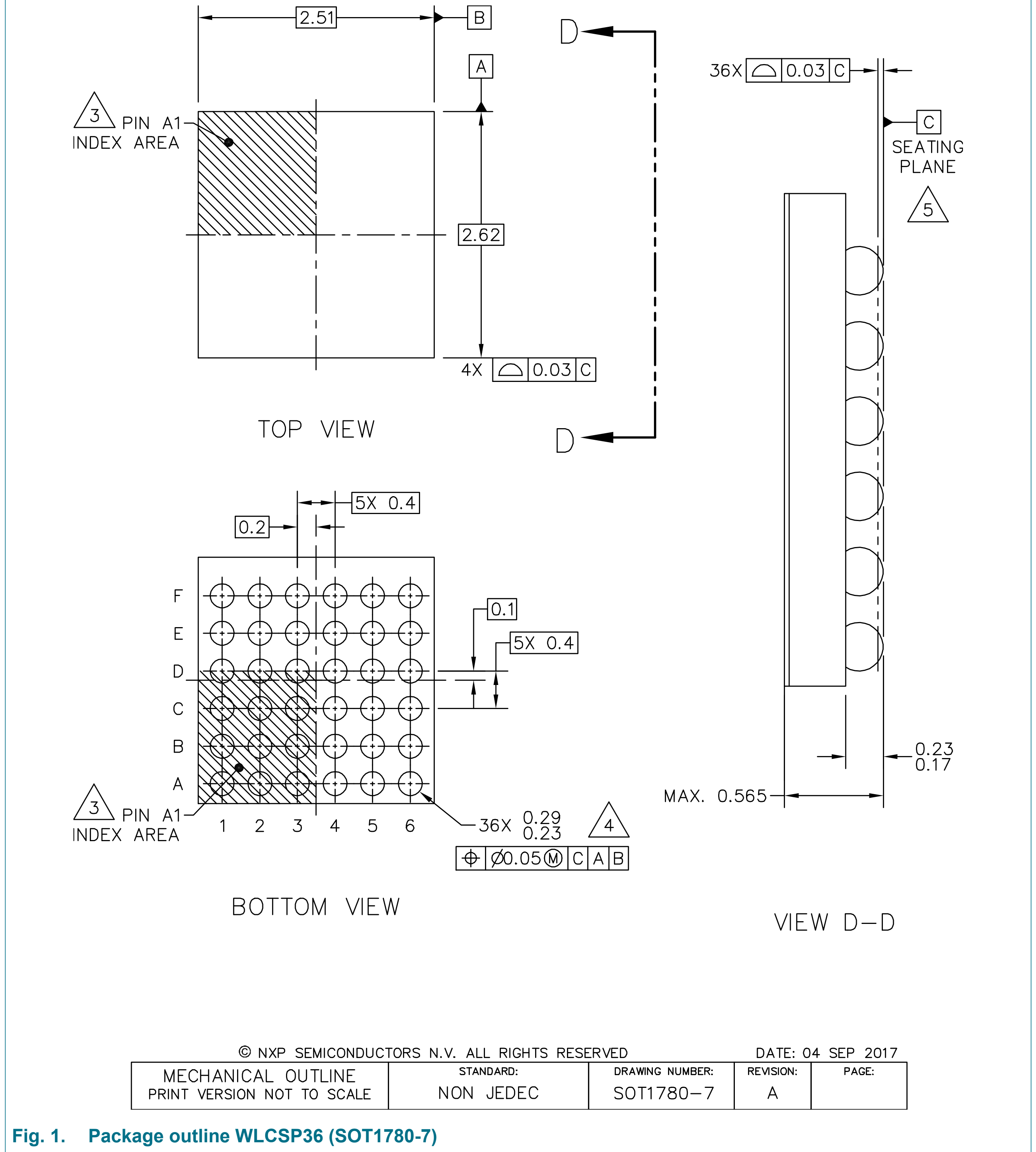

Fig. 1. Package outline WLCSP36 (SOT1780-7)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

Fig. 2. Package outline note WLCSP36 (SOT1780-7)

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3. Soldering

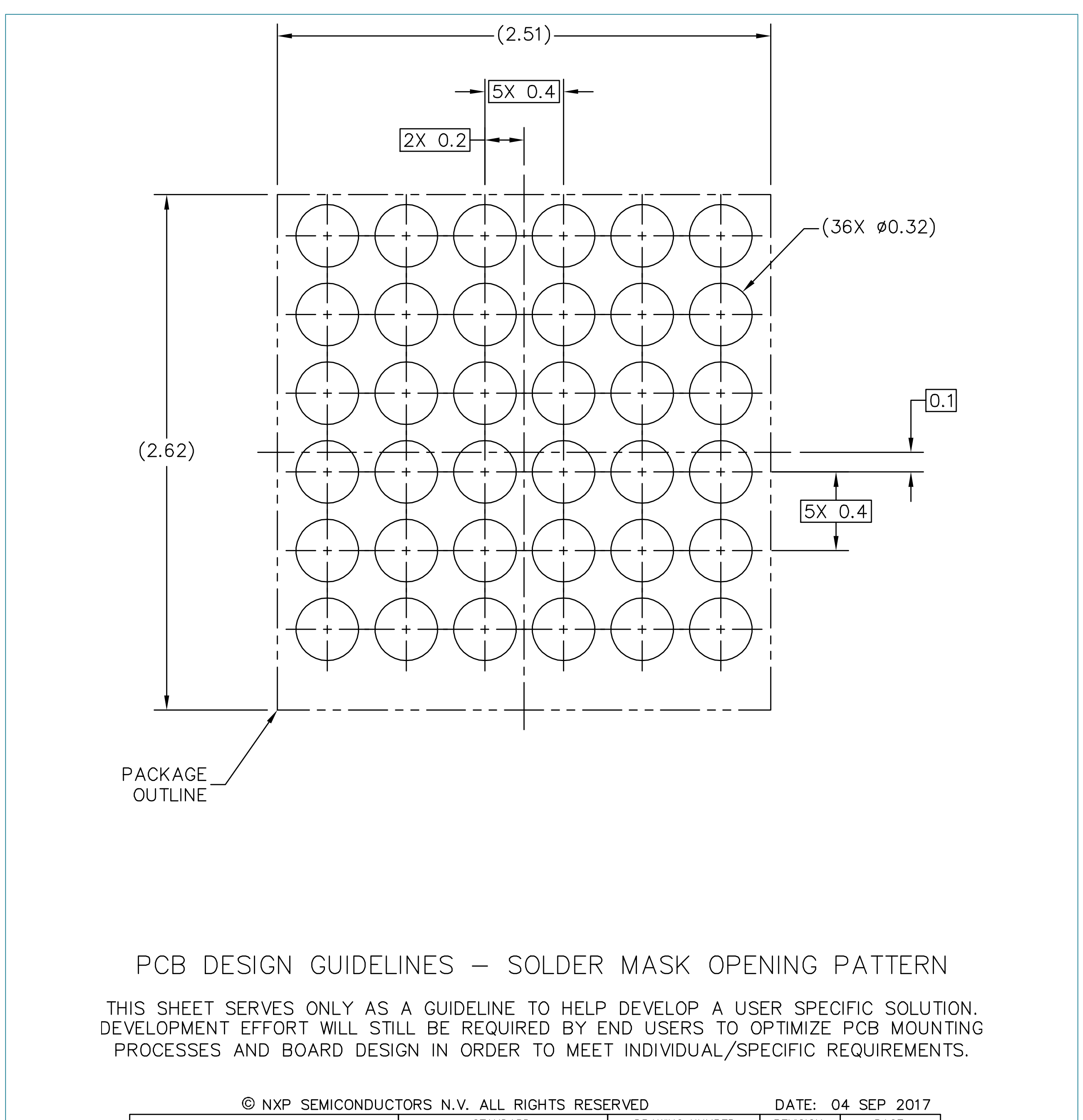

Fig. 3. Reflow soldering footprint for WLCSP36 (SOT1780-7)

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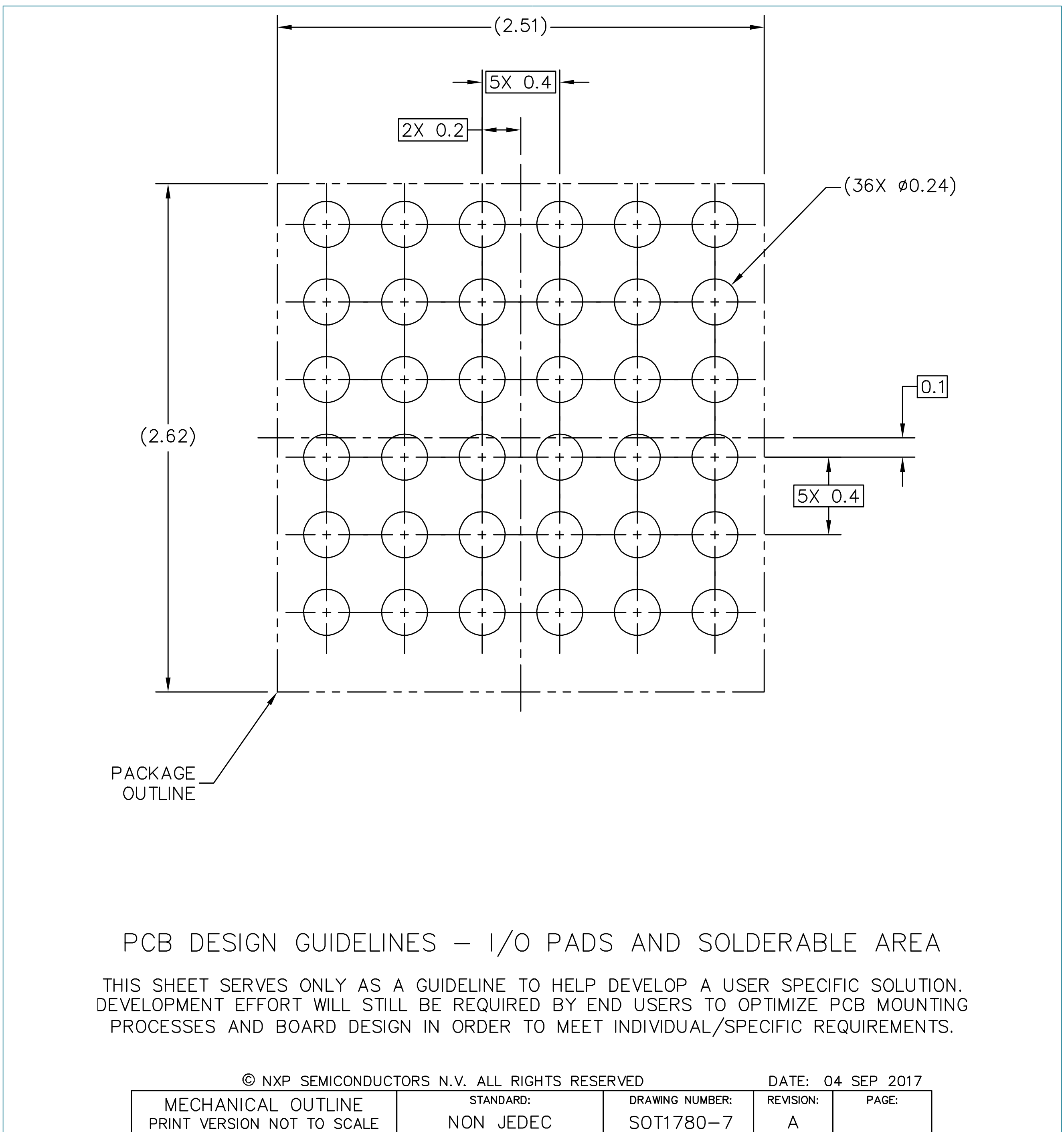

Fig. 4. Reflow soldering footprint part2 for WLCSP36 (SOT1780-7)

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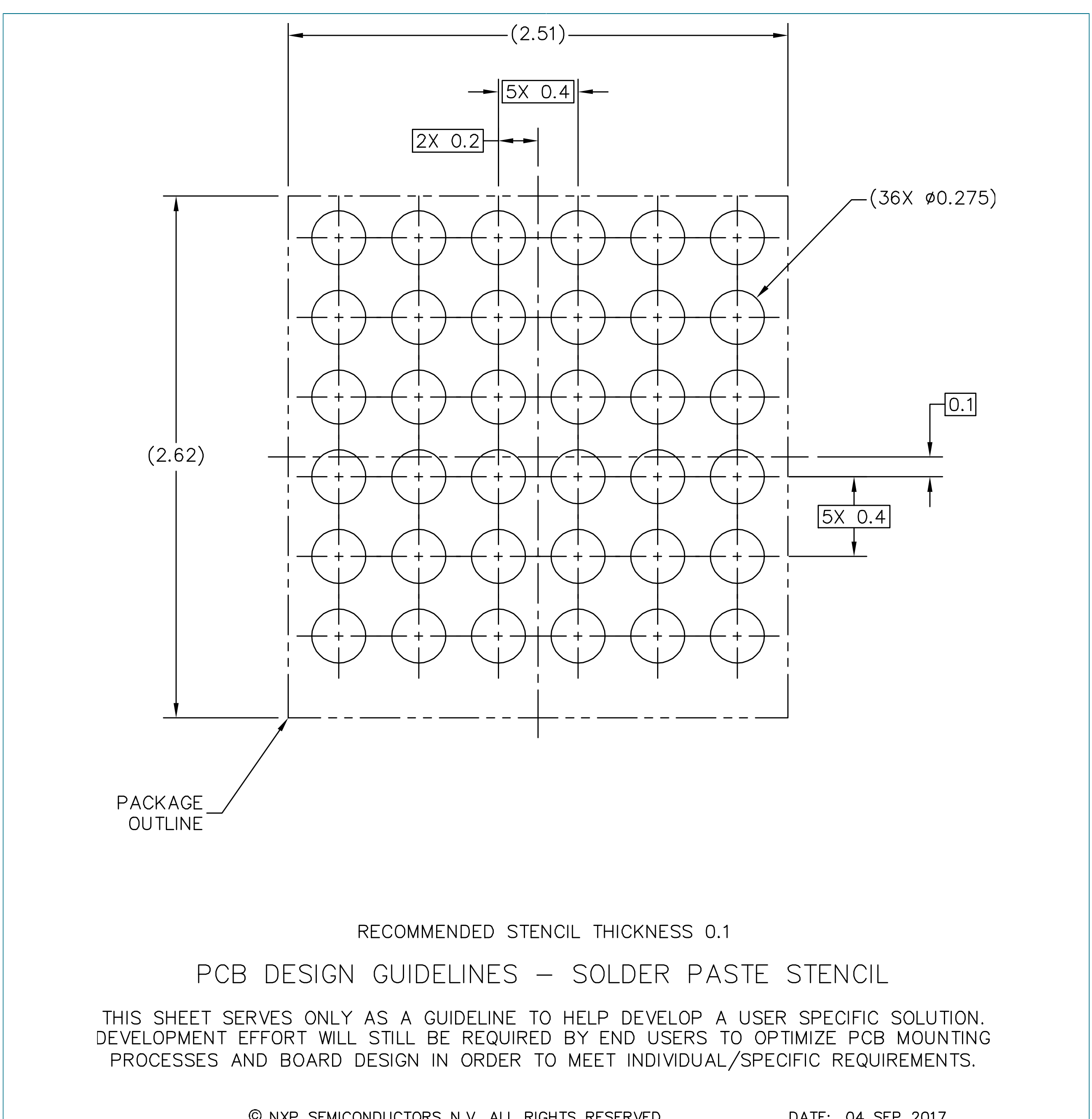

Fig. 5. Reflow soldering footprint part3 for WLCSP36 (SOT1780-7)

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